


Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H743BGT6	P8UH*450XXXV	A	9998	21-01-2021
	Amount	UoM	Unit type	ST ECOPACK Grade
	2240.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFP	28x28x1.4	208	L Bend	
Comment	Package : UH LQFP 208 28x28x1.4 1.0 7147657			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-25th June 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	P8UH*450XXXV				7999999.0	999999.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	16.439	mg	supplier	die	Silicon (Si)	7440-21-3		15.697	mg	954863	7008
				supplier	metallization	Aluminium (Al)	7429-90-5		0.088	mg	5353	39
				supplier	metallization	Copper (Cu)	7440-50-8		0.276	mg	16789	123
				supplier	passivation	Nickel (Ni)	7440-02-0		0.001	mg	61	0
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.045	mg	2737	20
				supplier	metallization	Titanium (Ti)	7440-32-6		0.008	mg	487	4
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	61	0
				supplier	Passivation	Silicon Oxide	7631-86-9		0.323	mg	19648	144
				supplier	ALLOY	Copper (Cu)	7440-50-8		422.278	mg	974500	188517
LEADFRAME (MHT - C194)	M-011 Other inorganic materials	433.328	mg	supplier	ALLOY	Iron (Fe)	7439-89-6		10.400	mg	24000	4643
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.520	mg	1200	232
				supplier	ALLOY	Metallic Phosphorous (P)	7723-14-0		0.130	mg	300	58
LEADFRAME (MHT - Ag Plating)	M-011 Other inorganic materials	1.592	mg	supplier	COATING	Silver(Ag)	7440-22-4		1.592	mg	1000000	711
DIE ATTACH (Evertech - AP4200)	M-011 Other inorganic materials	2.572	mg	supplier	GLUE	Silver(Ag)	7440-22-4		2.006	mg	780000	896
				supplier	GLUE	Phenolic Resin	9003-35-4		0.039	mg	15000	17
				supplier	GLUE	Ethylene glycol monobutyl ether acetate	112-07-2		0.103	mg	40000	46
				supplier	GLUE	Polymer with oxirane and Phenol	9003-36-5		0.386	mg	150000	172
				supplier	GLUE	1,4-Butanedioldiglycidyl Ether	2425-79-8		0.039	mg	15000	17
BONDING WIRE (Hesung - Au HTS V	M-011 Other inorganic materials	5.680	mg	supplier	BONDING WIRE	Gold (Au)	7440-57-5		5.680	mg	999960	2536
				supplier	BONDING WIRE	Calcium (Ca)	7440-70-2		0.000	mg	40	0
BONDING WIRE (Hesung - Au HTS W	M-011 Other inorganic materials	0.057	mg	supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.057	mg	1000000	25
ENCAPSULATION (Sumitomo -G6315H	M-011 Other inorganic materials	1768.982	mg	supplier	MOLDING COMPOUND	Epoxy Resin A	Proprietary		53.092	mg	30013	23702
				supplier	MOLDING COMPOUND	Epoxy resin B	85954-11-6		70.789	mg	40017	31602
				supplier	MOLDING COMPOUND	Silica Amorphous A (SiO3)	60676-86-0		1238.064	mg	699874	552707
				supplier	MOLDING COMPOUND	Silica Amorphous B (SiO3)	7631-86-9		274.307	mg	155065	122459
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		8.849	mg	5002	3950
FINISHING (Sytron - Sn100)	M-011 Other inorganic materials	11.350	mg	supplier	MOLDING COMPOUND	Phenol Resin	205830-20-2		123.881	mg	70029	55304
				supplier	COATING	Tin (Sn)	7440-31-5		11.350	mg	1000000	5067